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(54) Title: A SILICA-BASED SLURRY

(57) Abstract: This invention relates to a slurry composition and a method of its preparation. In particular, the slurry composition of the present invention includes a silica wherein the silica comprises a surface modification. The silica-based slurry of the present invention is suitable for polishing articles and especially useful for chemical-mechanical planarization ("CMP") of semiconductor and other microelectronic substrates.